

EC1-S-6.527M TR **ITEM DESCRIPTION**

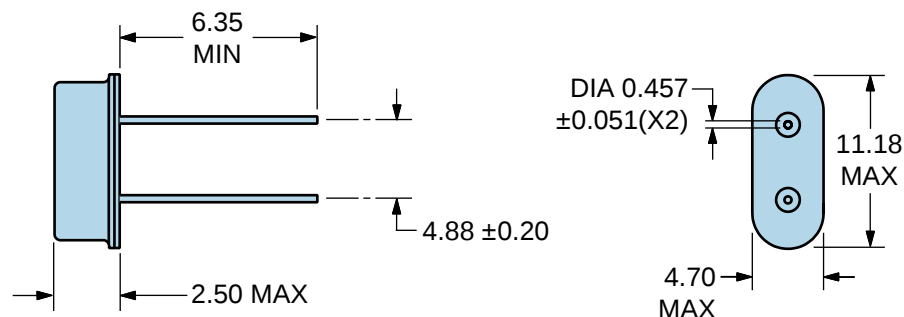
Quartz Crystal Resonator HC49/US Short Thru-Hole 2.5mm Height Metal Resistance Weld Seal 6.527MHz $\pm 50\text{ppm}$ at 25°C, $\pm 100\text{ppm}$ over 0°C to +70°C Series Resonant

ELECTRICAL SPECIFICATIONS

Nominal Frequency	6.527MHz
Frequency Tolerance/Stability	$\pm 50\text{ppm}$ at 25°C, $\pm 100\text{ppm}$ over 0°C to +70°C
Aging at 25°C	$\pm 5\text{ppm/year}$ Maximum
Load Capacitance	Series Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	120 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

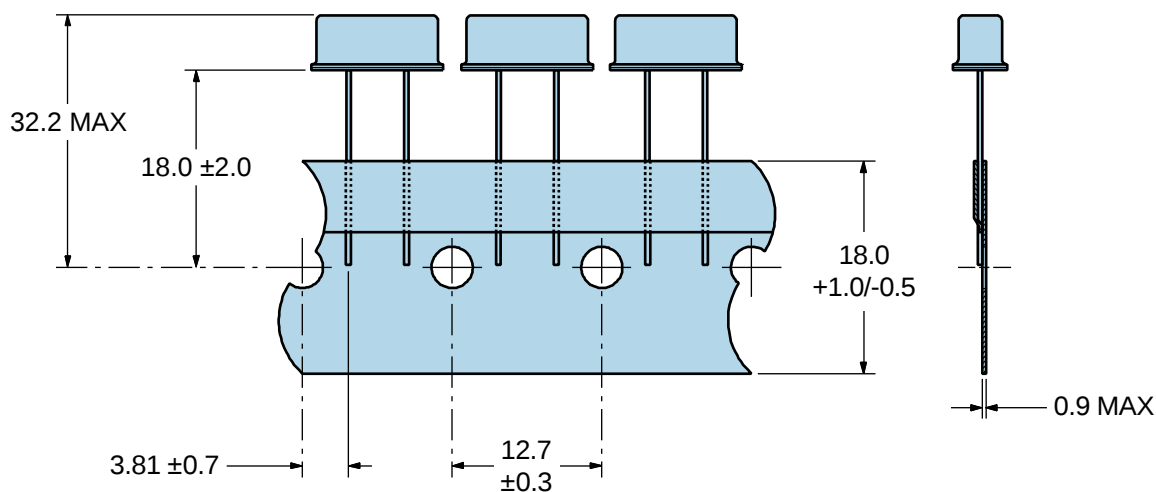
EC1-S-6.527M TR **MECHANICAL DIMENSIONS (all dimensions in millimeters)**

LINE	MARKING
1	E6.5270M <i>E=EclipseTek Designator</i> <i>M=Frequency Unit of Measure</i>

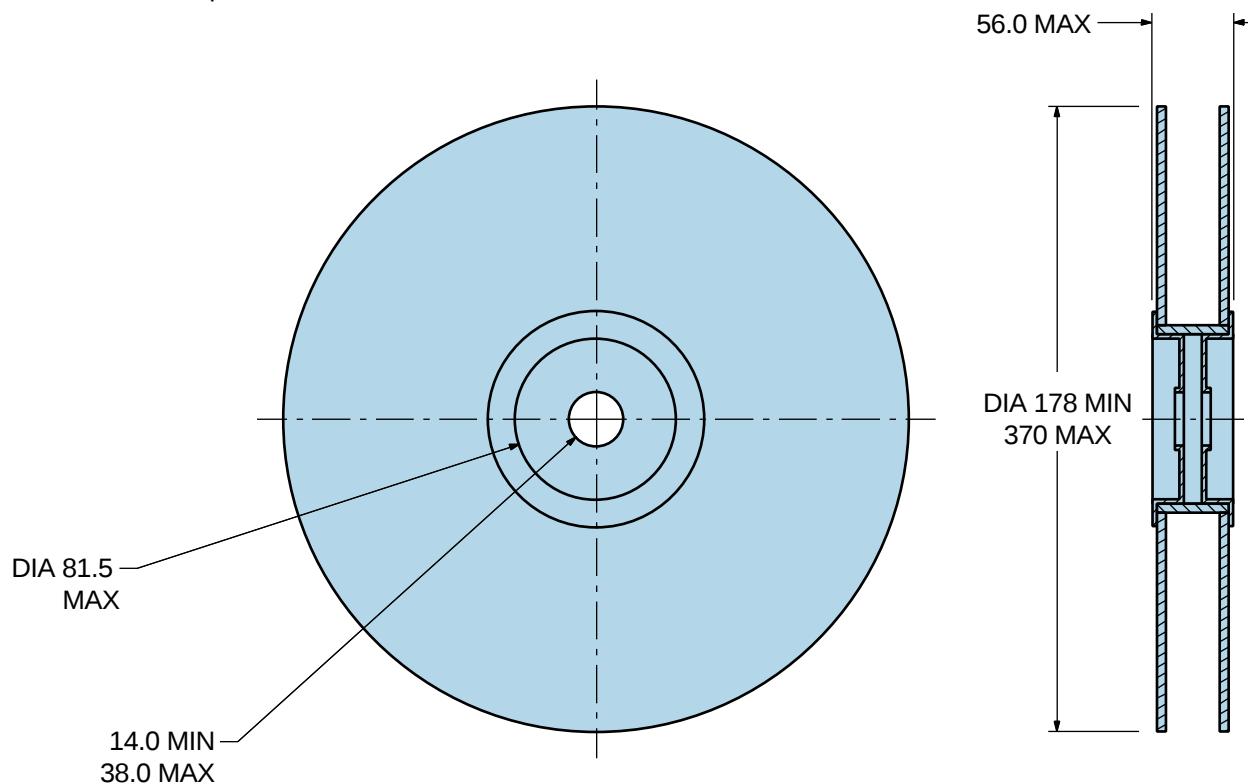
EC1-S-6.527M TR

Tape & Reel Dimensions

All Dimensions in Millimeters
Compliant to EIA-481



*Compliant to EIA 468B



Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder) Time (t)

T_s MAX to T_l (Ramp-up Rate)	3°C/Second Maximum
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Preheat

- Temperature Minimum (T_s MIN)	150°C
- Temperature Typical (T_s TYP)	175°C
- Temperature Maximum (T_s MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds

Ramp-up Rate (T_l to T_p)	3°C/Second Maximum
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Time Maintained Above:

- Temperature (T_l)	217°C
- Time (t_L)	60 - 150 Seconds

Peak Temperature (T_p)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (T_p Target)	250°C +0/-5°C
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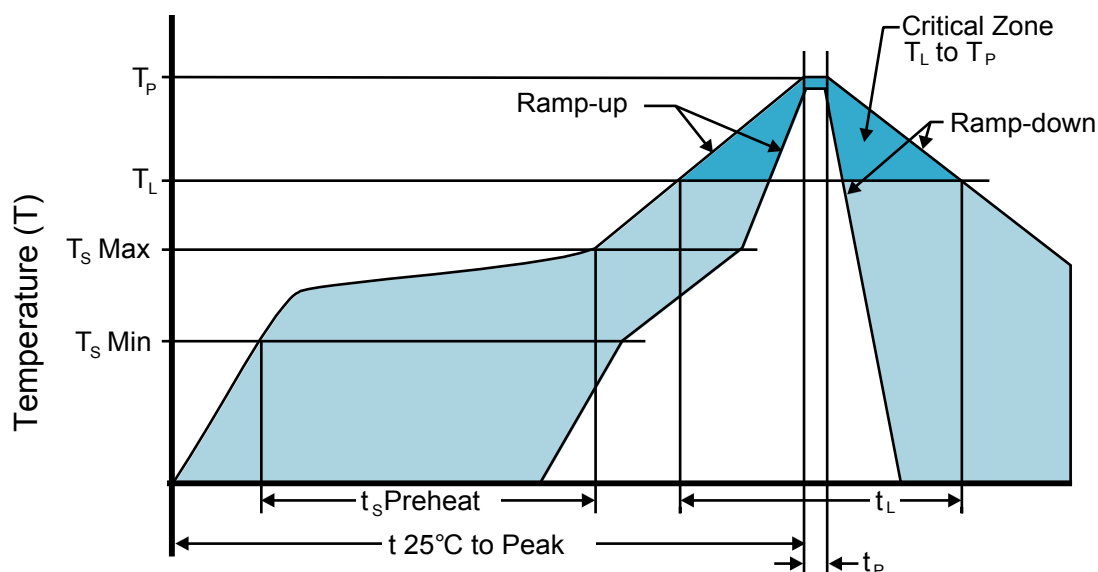
Time within 5°C of actual peak (t_p)	20 - 40 Seconds
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Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder) Time (t)

Ts MAX to Tl (Ramp-up Rate) 5°C/Second Maximum

Preheat

- Temperature Minimum (Ts MIN) N/A
- Temperature Typical (Ts TYP) 150°C
- Temperature Maximum (Ts MAX) N/A
- Time (ts MIN) 30 - 60 Seconds

Ramp-up Rate (Tl to Tp) 5°C/Second Maximum

Time Maintained Above:

- Temperature (Tl) 150°C
- Time (tl) 200 Seconds Maximum

Peak Temperature (Tp) 245°C Maximum

Target Peak Temperature (Tp Target) 245°C Maximum 1 Time / 235°C Maximum 2 Times

Time within 5°C of actual peak (tp) 5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.